

**FEATURES**

- **HIGH POWER**  
P1dB=42.0dBm at 9.5GHz to 10.5GHz
- **HIGH GAIN**  
G1dB=7.0dB at 9.5GHz to 10.5GHz
- **BROAD BAND INTERNALLY MATCHED FET**
- **HERMETICALLY SEALED PACKAGE**

**RF PERFORMANCE SPECIFICATIONS ( Ta= 25°C )**

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Compression Point	P1dB	VDS= 9V f = 9.5 to 10.5GHz	dBm	41.0	42.0	—
Power Gain at 1dB Compression Point	G1dB		dB	6.0	7.0	—
Drain Current	IDS1		A	—	4.5	5.5
Gain Flatness	ΔG		dB	—	—	±0.8
Power Added Efficiency	ηadd		%	—	31	—
3 <sup>rd</sup> Order Intermodulation Distortion	IM3	Two-tone Test Po=30.0 dBm	dBc	-42	-45	—
Drain Current	IDS2	(Single Carrier Level)	A	—	4.5	5.5
Channel Temperature Rise	ΔTch	(VDS X IDS + Pin - P1dB) X Rth(c-c)	°C	—	—	100

**ELECTRICAL CHARACTERISTICS ( Ta= 25°C )**

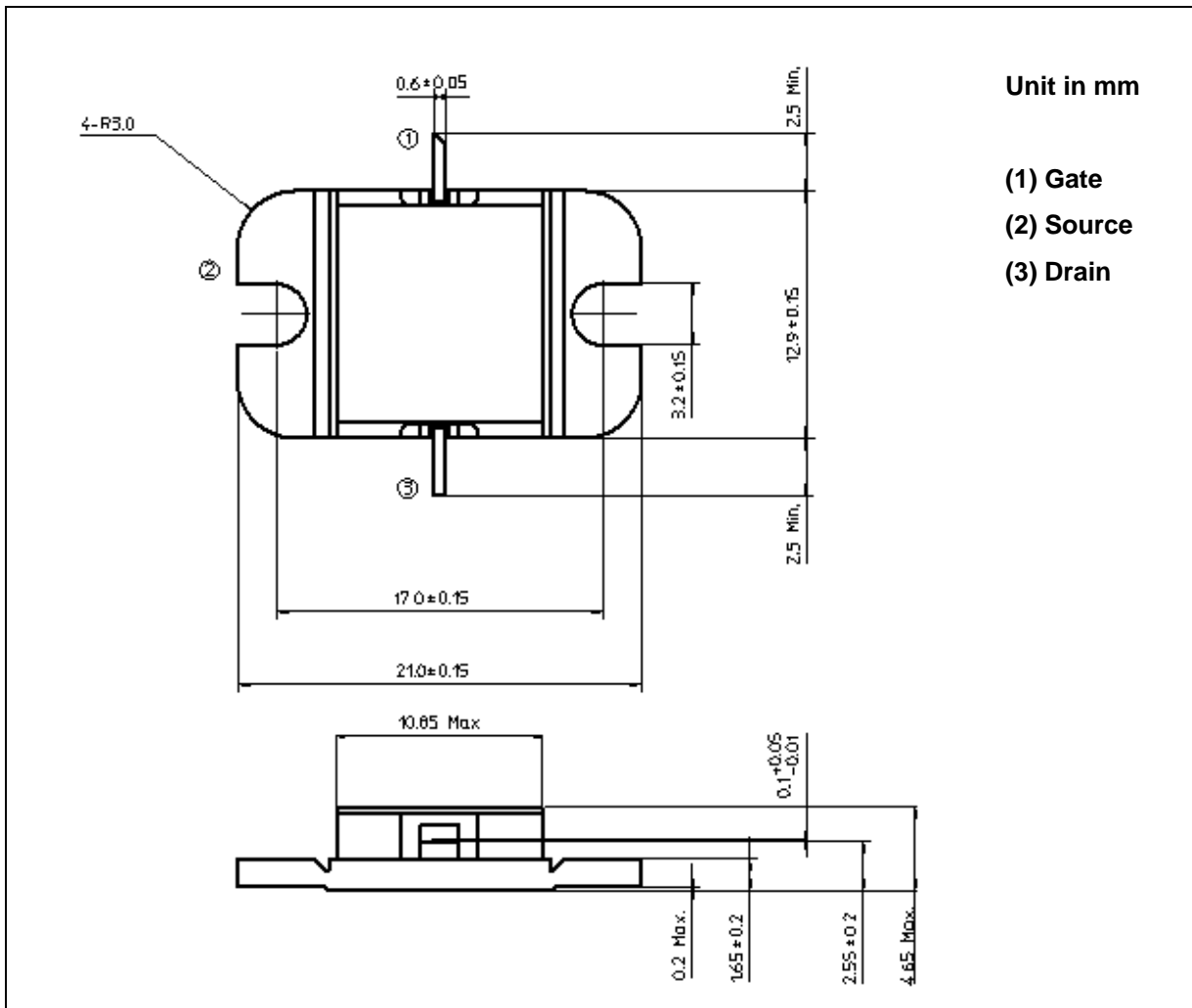
CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	VDS= 3V IDS= 4.8A	mS	—	3000	—
Pinch-off Voltage	VGSoff	VDS= 3V IDS= 145mA	V	-1.5	-3.0	-4.5
Saturated Drain Current	IDSS	VDS= 3V VGS= 0V	A	—	10.0	—
Gate-Source Breakdown Voltage	VGSO	IGS= -145μA	V	-5	—	—
Thermal Resistance	Rth(c-c)	Channel to Case	°C/W	—	2.0	2.5

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**ABSOLUTE MAXIMUM RATINGS ( Ta= 25°C )**

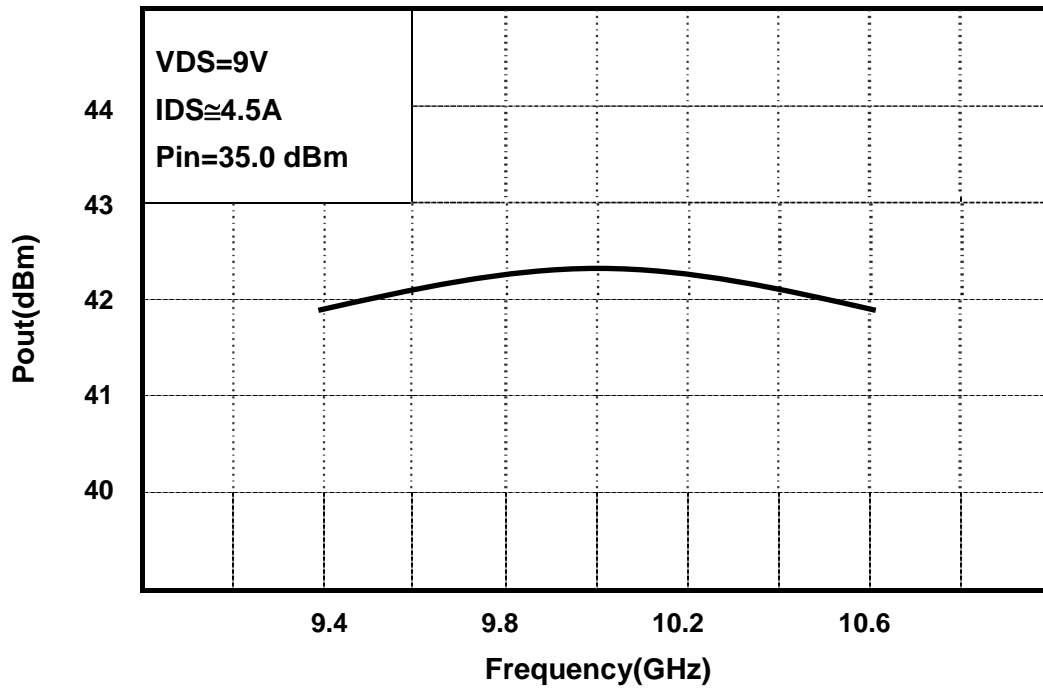
CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	VDS	V	15
Gate-Source Voltage	VGS	V	-5
Drain Current	IDS	A	11.5
Total Power Dissipation (Tc= 25 °C)	PT	W	60.0
Channel Temperature	Tch	°C	175
Storage	Tstg	°C	-65 ~ +175

**PACKAGE OUTLINE (2-11C1B)****HANDLING PRECAUTIONS FOR PACKAGE MODEL**

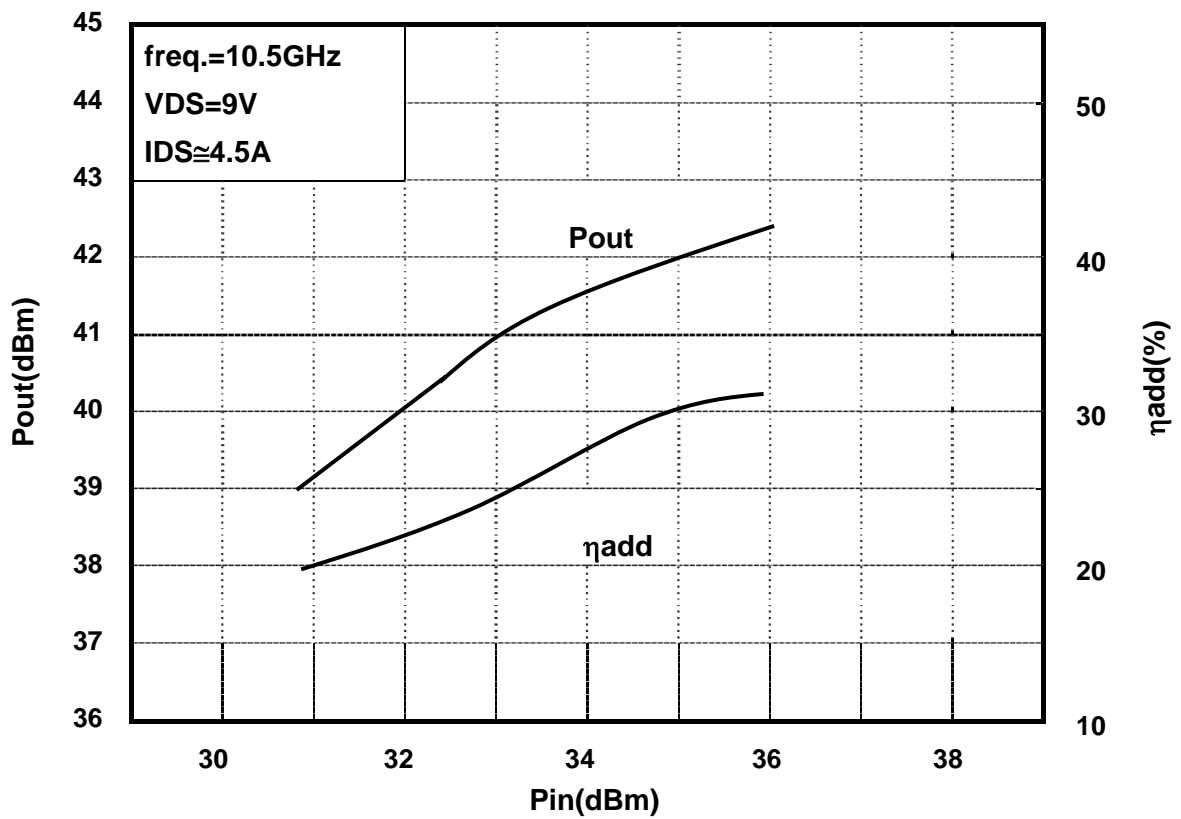
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

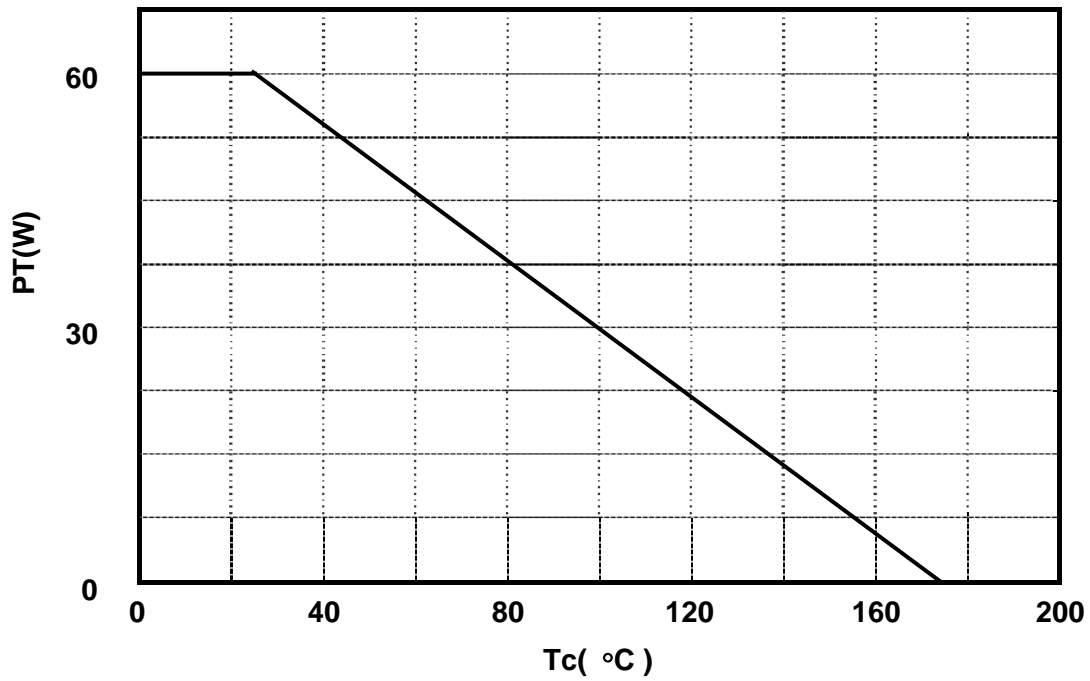
## RF PERFORMANCE

Output Power (Pout) vs. Frequency



Output Power(Pout) vs. Input Power(Pin)



**Power Dissipation(PT) vs. Case Temperature(Tc)****IM3 vs. Output Power Characteristics**